

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY DOCKET NO. SJ09-2000-0067US1	SERIAL NO. 09/764,019
	APPLICANT Hsiao et al.	
	FILING DATE January 16, 2001	GROUP 2652

## U. S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
RST	AA	5,047,115	9/1991	Charlet et al.	156	643	
RST	AB	5,356,478	10/1994	Chen et al.	134	1	
RST	AC	6,260,256 B1	7/2001	Sasaki	29	603.01	
	AD						
	AE						
	AF						
	AG						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS	SUBCLASS	TRANSLATION YES NO
RST	AH	02230505	9/1990	Japan	NEC Corp.	<del>G11B</del>	<del>5/31</del>	X
RST	AI	11283216	10/1999	Japan	TDK Corp.	<del>G11B</del>	<del>5/31</del>	X
RST	AJ	PCT/EP01/15254						
	AK							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	AL		
	AM		

EXAMINER <i>R.S. Turner</i>	DATE CONSIDERED <i>8/04</i>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

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## U. S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>RST</i>	AA	5,059,278	10/1991	Cohen et al.	156	643	
	AB						
	AC						
	AD						
	AE						
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	AG						
	AH						
	AI						
	AJ						
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	AL							
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	AN							
	AO							
	AP							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>RST</i>	AQ		IBM Technical Disclosure Bulletin, Nov. 1992, "Alternate Method for Etching Copper Seed Layers."
<i>RST</i>	AR		IBM Technical Disclosure Bulletin, June 1995, "NiFe/Cu Seed Layer for Plating Coil Cu in Magnetic Recording Heads."
	AS		

EXAMINER <i>R. S. Tamm</i>	DATE CONSIDERED <i>8/04</i>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	